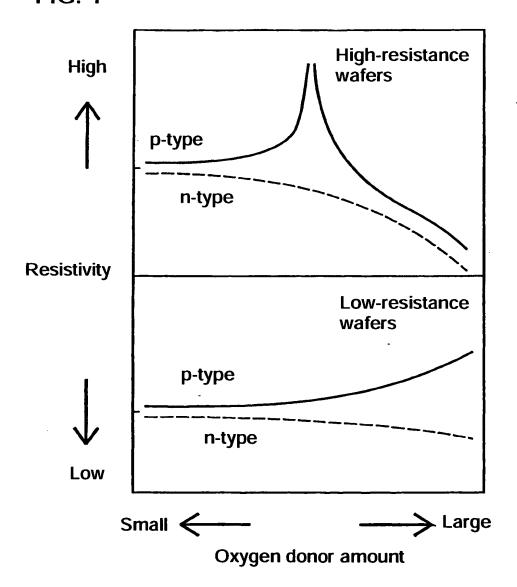
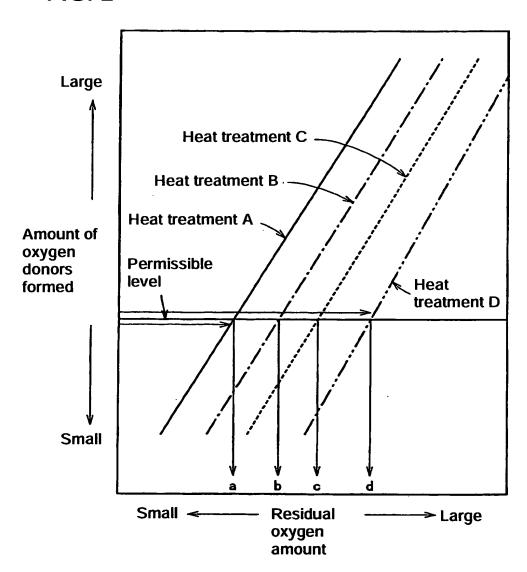
New U.S. Patent Application Inventor: Kazunari Kurita et al. Filed: 04/19/2006 Title: Process for Producing High-Resistance Silicon Wafers and... SHEET 1 of 5

FIG. 1



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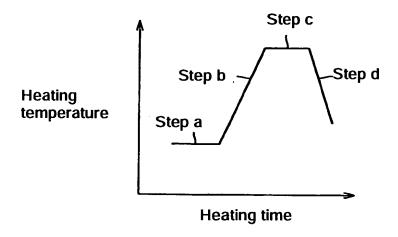
FIG. 2



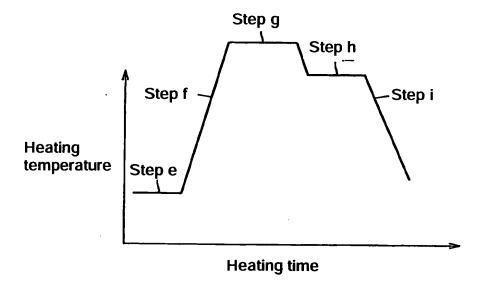
New U.S. Patent Application Inventor: Kazunari Kurita et al. Filed: 04/19/2006 Title: Process for Producing High-Resistance Silicon Wafers and... SHEET 3 of 5

FIG. 3

(a) First heat treatment



(b) Second heat treatment



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FIG. 4

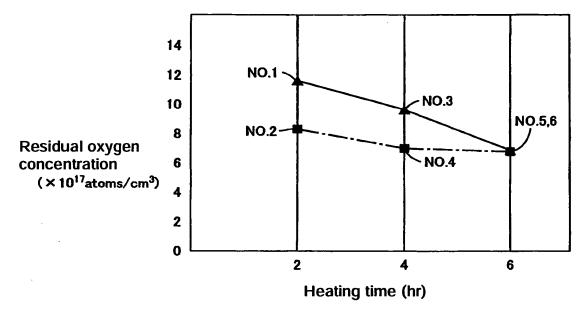
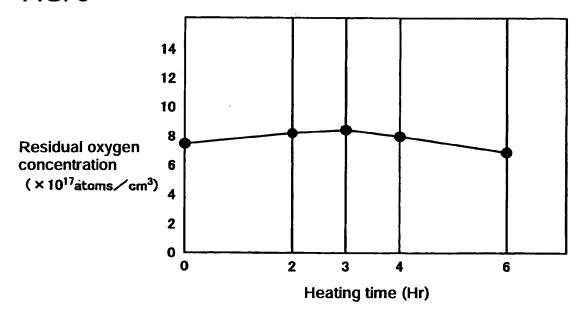


FIG. 5



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FIG. 6

Third heat treatment

